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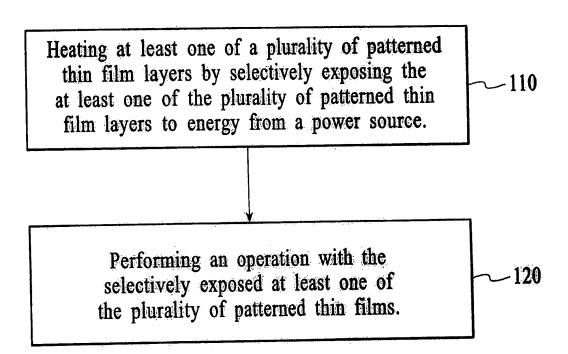
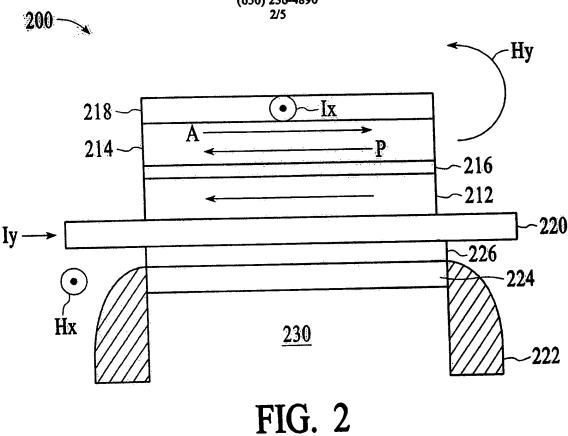
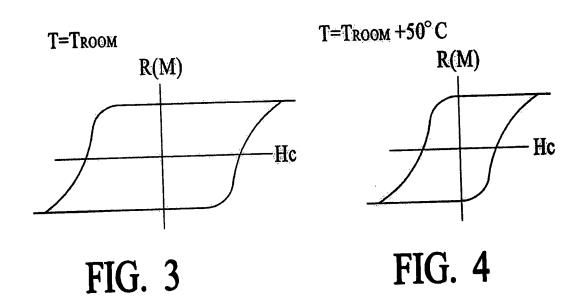


FIG. 1

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HPPDNO 200308744-1 A Thin Film Device and a Method of Providing Thermal Assistance Therein Nickel et al. Contact: Brian Short (650) 236-4890 3/5 511-Depositing a heater material (a) over a dielectric material. -512 510 (b) Creating trenches in the dielectric material. -520 521 Coating the trenches with (c) 531 a conductive material. -530 521 (d) Performing an anisotropic etch on the conductive material. 540 551 Depositing a planarizing (e) dielectric over the structure. 550 551 511 551 511 Etching back the **(f)** planarizing dielectric.

Depositing and patterning an SDT junction over the heater material wherein the SDT junction includes a free layer.

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FIG. 5

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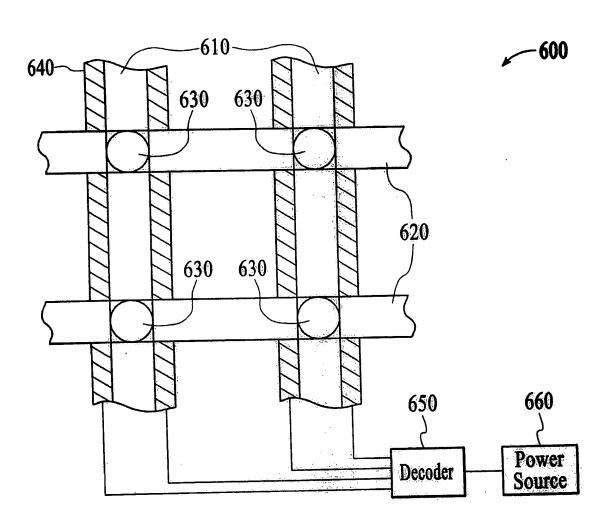


FIG. 6

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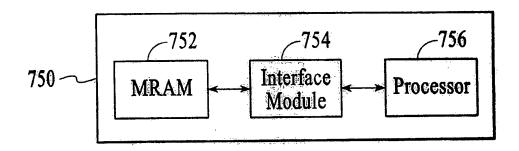


FIG. 7